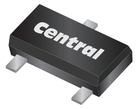
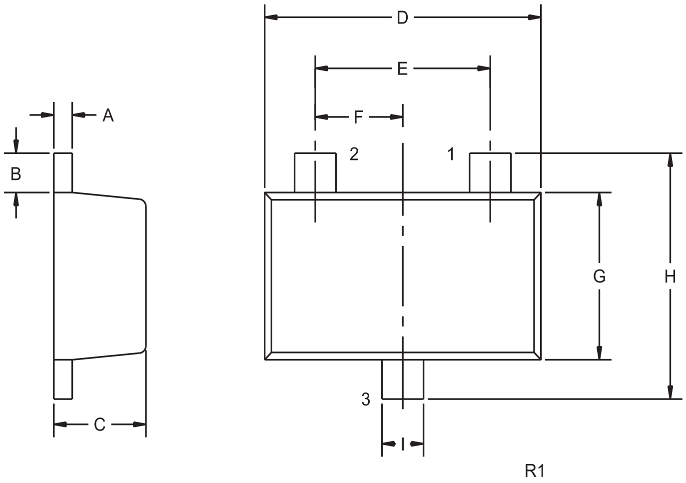
Package Details

SOT-23F Case



Mechanical Drawing



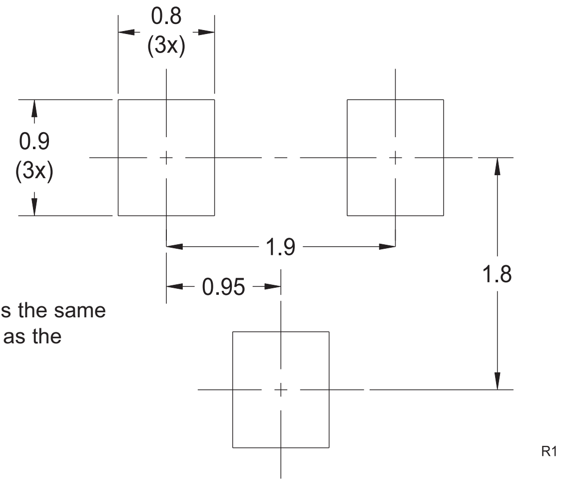
DIMENSIONS				
	INCHES		MILLIMETERS	
SYMBOL	MIN	MAX	MIN	MAX
A	0.004	0.008	0.10	0.20
B	0.012	0.020	0.30	0.50
C	0.031	0.039	0.80	1.00
D	0.110	0.118	2.80	3.00
E	0.075		1.90	
F	0.037		0.95	
G	0.059	0.067	1.50	1.70
H	0.091	0.098	2.30	2.50
I	0.014	0.018	0.35	0.45

SOT-23F (REV: R1)

Lead Code:
Reference individual
device datasheet.

Part Marking: 2-4 Character Alpha/Numeric Code

Mounting Pad Geometry (Dimensions in mm)

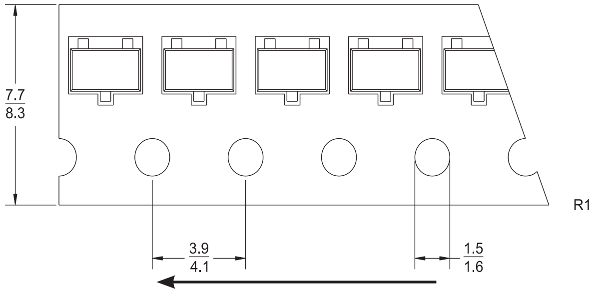


Note: The SOT-23F uses the same mounting pad geometry as the SOT-23.

R3 (4-March 2010)

Tape Dimensions and Orientation (Dimensions in mm)

Tape Width: 8mm



Direction of Unreeling

Devices are taped in accordance with Electronic Industries Association Standard EIA-481-1-A

Packaging Base

7” Reel = 3,000 pcs.

Reel Labeling Information

Each reel is labeled with the following information:
Central Part Number, Customer Part Number, Purchase Order Number, Quantity, Lot Number, Date Code, Ship Date and Marking Code.

Reel Packing Information

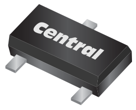
Reel Size	Reels per Box (Maximum)	Parts per Box (Maximum)	Box Dimensions		Shipping Weight (Max.)	
			INCH	CM	LB	KG
7”	9	27,000	9x9x5	23x23x13	4	2
	18	54,000	9x9x9	23x23x23	7	4
	40	120,000	21x9x9	53x23x23	14	7
	108	324,000	27x9x17	69x23x43	39	18

Ordering Information

- For devices taped and reeled on 7” reels, add TR suffix to part number.
- All SMDs are available in small quantities for prototype and manual placement applications.

Material Composition Specification

SOT-23F Case



Device average mass . . . . **11.0 mg**

Fluctuation margin . . . . **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	0.64%	0.07	Si	7440-21-3	0.64%	0.07	6,364
bond wire	gold	0.2%	0.02	Au	7440-57-5	0.2%	0.022	2,000
leadframe	Cu alloy w/ silver plating	38.38%	4.22	Cu	7440-50-8	37.65%	4.141	376,455
				Fe	7439-89-6	0.04%	0.004	364
				Ag	7440-22-4	0.7%	0.077	7,000
die attach	silver epoxy	0.43%	0.05	Ag	7440-22-4	0.32%	0.035	3,182
				epoxy resin	Proprietary	0.11%	0.012	1,091
encapsulation*	EMC	59.47%	6.54	silica	7631-86-9	42.89%	4.718	428,909
				epoxy resin	Proprietary	14.95%	1.644	149,455
				Sb_2O_3	1309-64-4	1.19%	0.131	11,909
				TBBA	79-94-7	0.3%	0.033	3,000
				carbon	1333-86-4	0.15%	0.016	1,455
	EMC GREEN	59.47%	6.54	silica	60676-86-0	39.34%	4.327	393,364
				epoxy resin	37382079-9	6.82%	0.75	68,182
				phenol resin	9003-35-4	6.82%	0.75	68,182
				carbon black	1333-86-4	0.31%	0.034	3,091
				metal hydroxide	1309-42-8	6.19%	0.681	61,909
plating	matte tin	0.88%	0.1	Sn	7440-31-5	0.88%	0.097	8,818

*EMC GREEN molding compound is Halogen-Free.

R6 (3-June 2011)